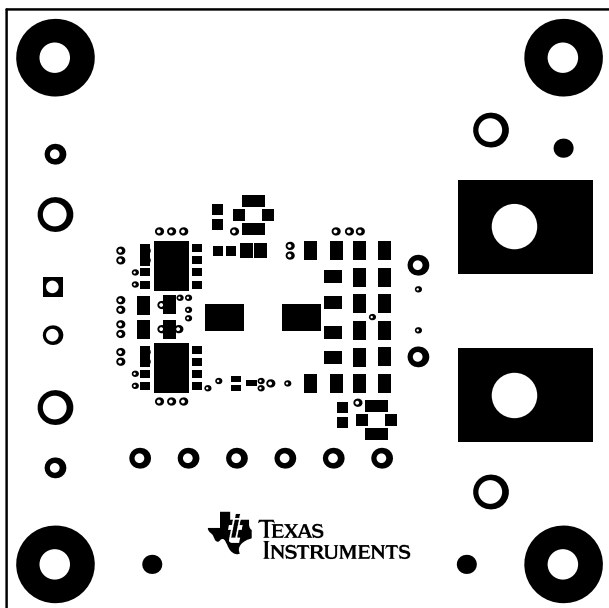
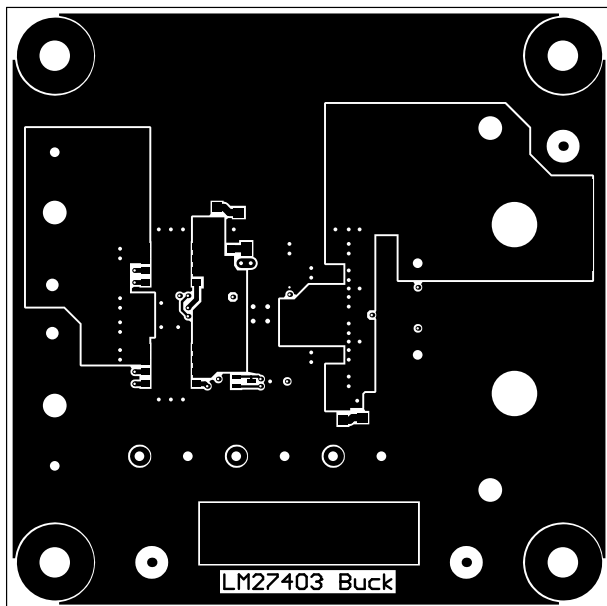


| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP7935 | REV: B | SUN REV: Not In VersionControl |
| LAYER NAME = Top Overlay | | | |
| PLOT NAME = Top Overlay | GENERATED : 4/25/2013 1:06:32 PM | TEXAS INSTRUMENTS | |




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|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP7935 | REV: B | SUN REV: Not In VersionControl |
| LAYER NAME = Top Solder | | | |
| PLOT NAME = Top Solder Mask | GENERATED : 4/25/2013 1:06:33 PM | TEXAS INSTRUMENTS | |



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: PMP7935

REV: B

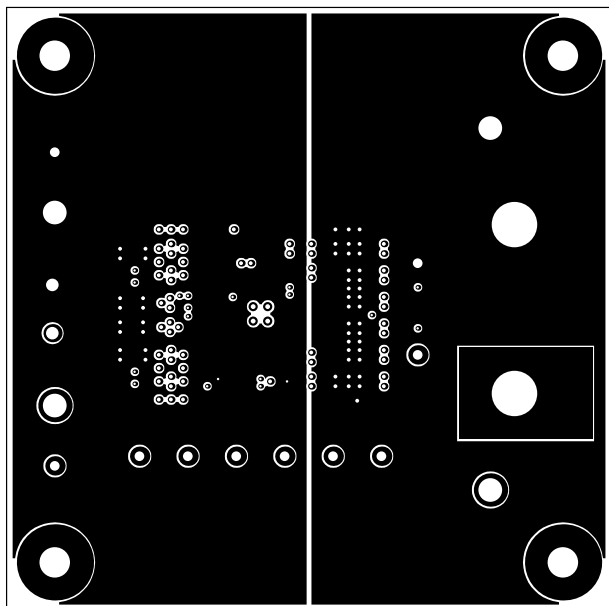
SUN REV: Not In VersionControl

LAYER NAME = Top Layer

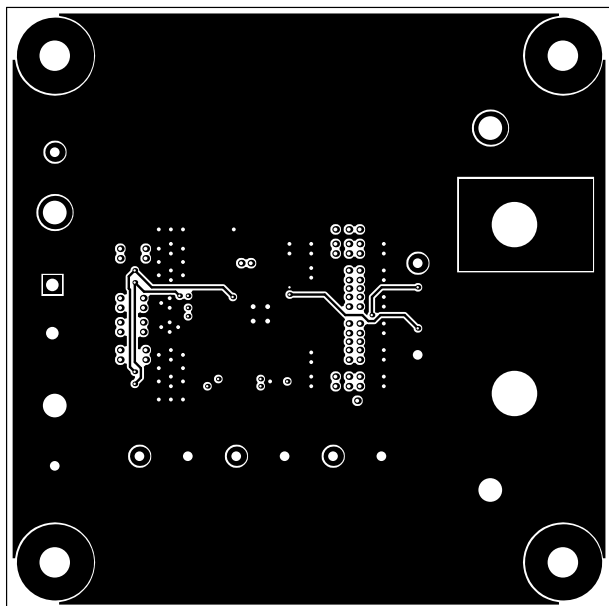
PLOT NAME = Top Layer

GENERATED : 4/25/2013 1:06:33 PM

TEXAS INSTRUMENTS



| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP7935 | REV: B | SUN REV: Not In VersionControl |
| LAYER NAME = MidLayer1 | | | |
| PLOT NAME = MidLayer1 | GENERATED : 4/25/2013 1:06:34 PM | TEXAS INSTRUMENTS | |



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: PMP7935

REV: B

SUN REV: Not In VersionControl

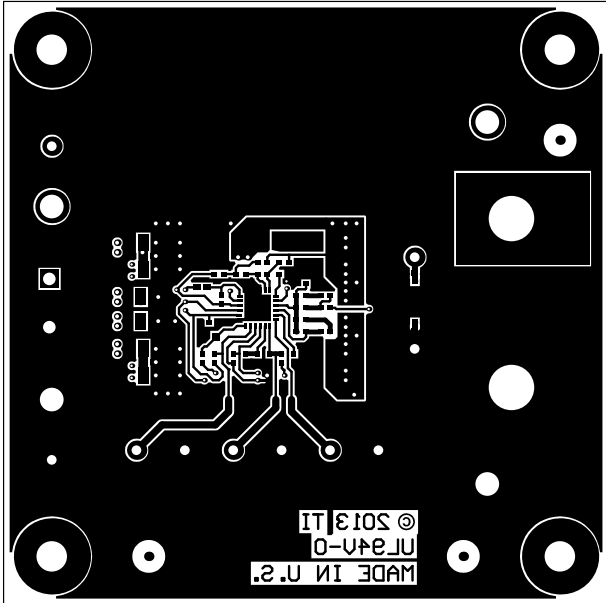
LAYER NAME = MidLayer2

PLOT NAME = MidLayer2

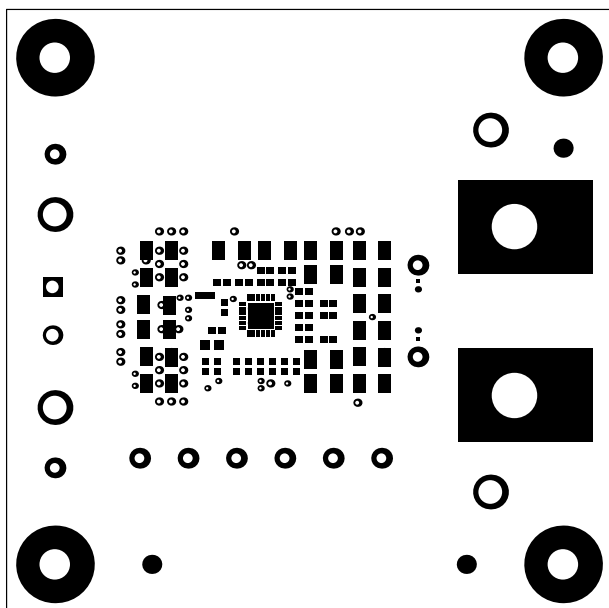
GENERATED : 4/25/2013 1:06:34 PM

TEXAS INSTRUMENTS

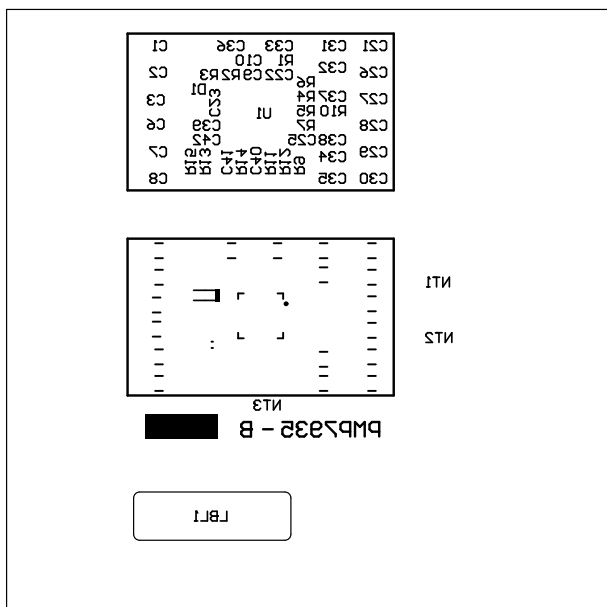
SUN Rev: Not In VersionControl



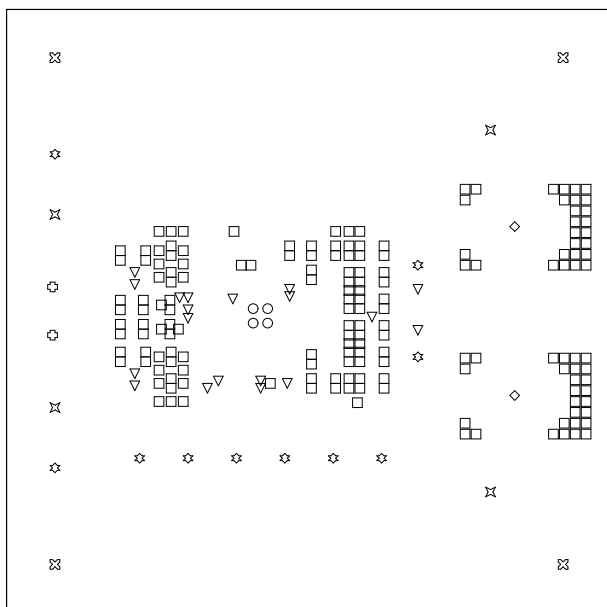
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP7935 | REV: B | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Layer | | | |
| PLOT NAME = Bottom Layer | GENERATED : 4/25/2013 1:06:35 PM | TEXAS INSTRUMENTS | |



| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP7935 | REV: B | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Solder | | | |
| PLOT NAME = Bottom Solder Mask | GENERATED : 4/25/2013 1:06:35 PM | TEXAS INSTRUMENTS | |



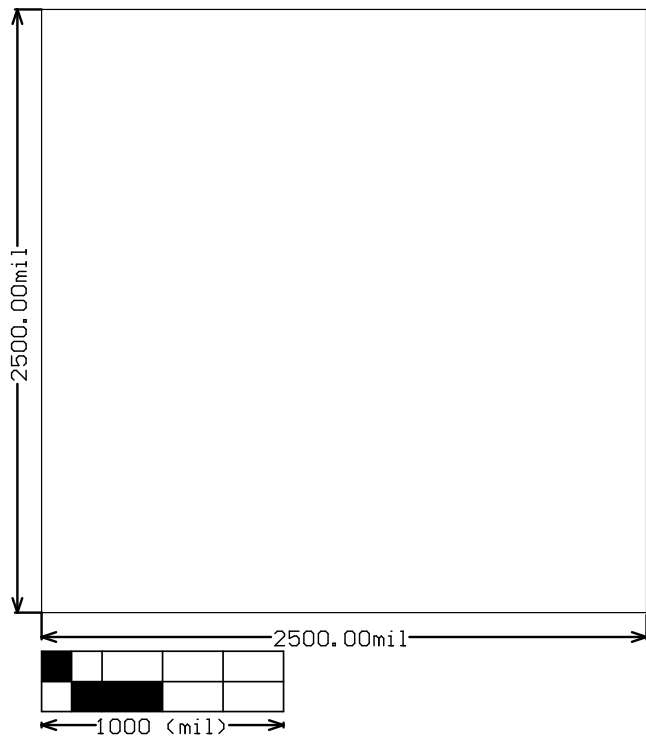
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP7935 | REV: B | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Overlay | | | |
| PLOT NAME = Bottom Overlay | GENERATED : 4/25/2013 1:06:36 PM | TEXAS INSTRUMENTS | |



| Symbol | Hit Count | Tool Size | Plated | Hole Type |
|--------|------------------|--------------------|--------|-----------|
| ▽ | 19 | 10mil (0.254mm) | PTH | Round |
| □ | 167 | 16mil (0.406mm) | PTH | Round |
| ○ | 4 | 20mil (0.508mm) | PTH | Round |
| ☆ | 10 | 40mil (1.016mm) | PTH | Round |
| ⊕ | 2 | 51.181mil (1.3mm) | PTH | Round |
| ⊗ | 4 | 98.425mil (2.5mm) | PTH | Round |
| ⊗ | 4 | 125.984mil (3.2mm) | PTH | Round |
| ◇ | 2 | 188mil (4.775mm) | PTH | Round |
| | 212 Total | | | |

Drill Table

| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP7935 | REV: B | SUN REV: Not In VersionControl |
| LAYER NAME = Drill Drawing | | | |
| PLOT NAME = Drill Drawing | GENERATED : 4/25/2013 1:06:36 PM | TEXAS INSTRUMENTS | |



| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP7935 | REV: B | SUN REV: Not In VersionControl |
| LAYER NAME = M2 Board Dimensions | | | |
| PLOT NAME = Board Dimensions | GENERATED : 4/25/2013 1:06:37 PM | TEXAS INSTRUMENTS | |

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